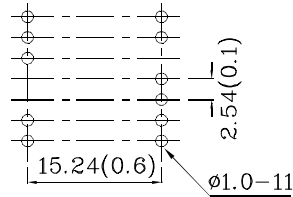


Features

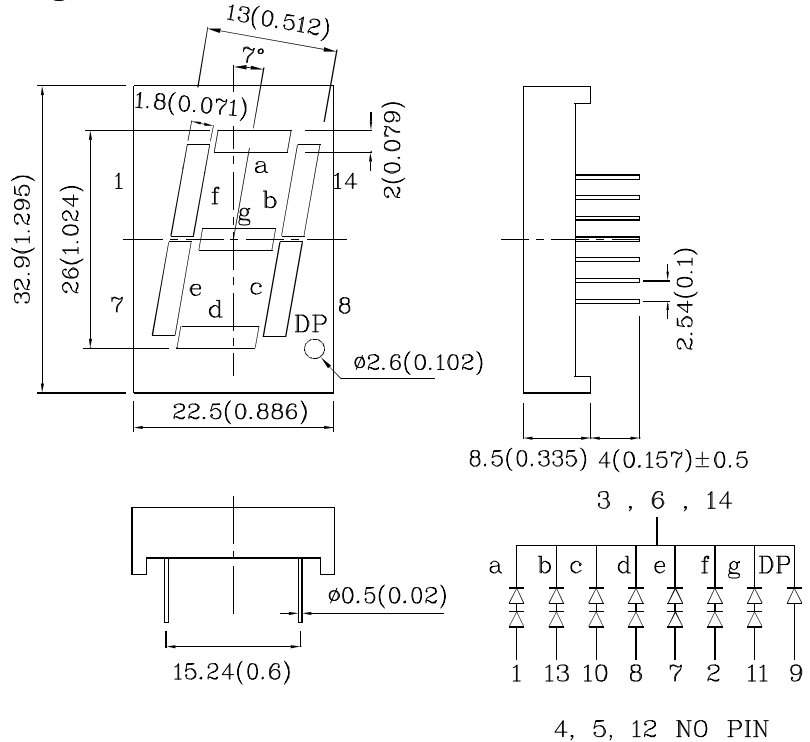
- Low power consumption
- Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant



RECOMMENDED PCB LAYOUT



Package Schematics



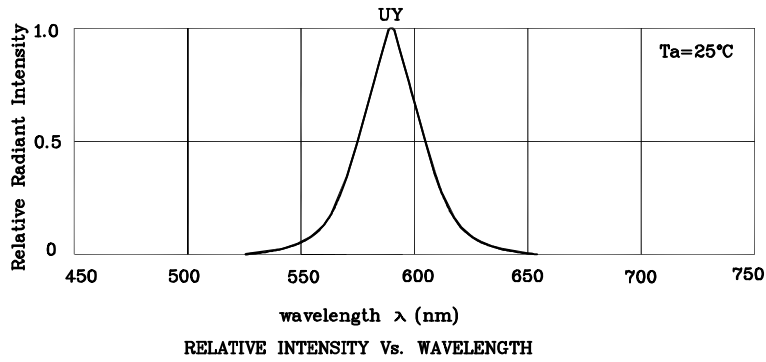
Notes:

1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01") unless otherwise noted.
2. Specifications are subject to change without notice.

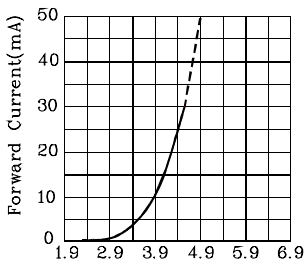
Absolute Maximum Ratings (T _A =25°C)		UY (GaAsP/GaP)	Unit
Reverse Voltage	V _R	5 (5)	V
Forward Current	I _F	30 (30)	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	140 (140)	mA
Power Dissipation	P _D	150 (75)	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds		

Operating Characteristics (T _A =25°C)		UY (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V _F	3.9 (1.95)	V
Forward Voltage (Max.) (I _F =10mA)	V _F	5 (2.5)	V
Reverse Current (Max.) (V _R =5V)	I _R	10 (10)	uA
Wavelength of Peak Emission (Typ.) (I _F =10mA)	λ _P	590	nm
Wavelength of Dominant Emission (Typ.) (I _F =10mA)	λ _D	588	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	35	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	20	pF

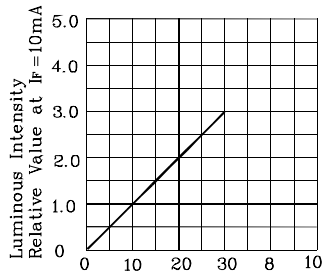
Part Number	Emitting Color	Emitting Material	Luminous Intensity (I _F =10mA) ucd		Wavelength nm λ _P	Description
			min.	typ.		
XDUY25C-1	Yellow	GaAsP/GaP	9000	22990	590	Common Cathode, Rt. Hand Decimal.



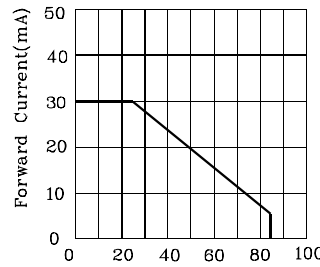
❖ UY



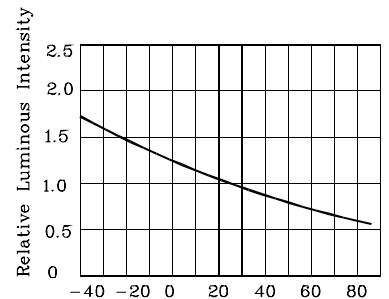
FORWARD CURRENT Vs. FORWARD VOLTAGE



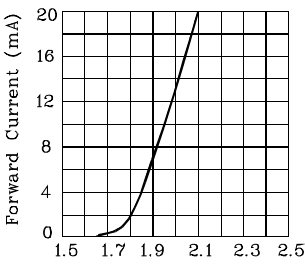
LUMINOUS INTENSITY Vs. FORWARD CURRENT



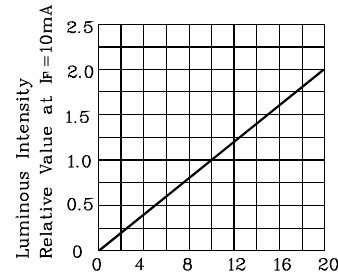
FORWARD CURRENT DERATING CURVE



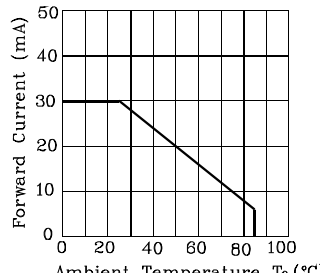
LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE



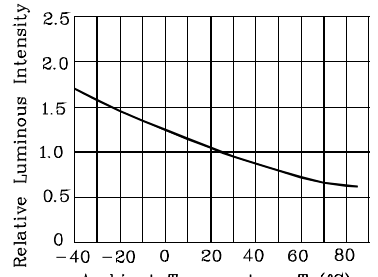
FORWARD CURRENT Vs. FORWARD VOLTAGE



LUMINOUS INTENSITY Vs. FORWARD CURRENT

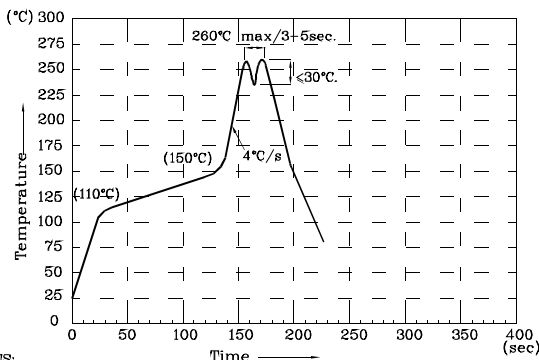


FORWARD CURRENT DERATING CURVE



LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE

Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering, the PCB top-surface temperature should be kept below 105°C.
5. No more than once.

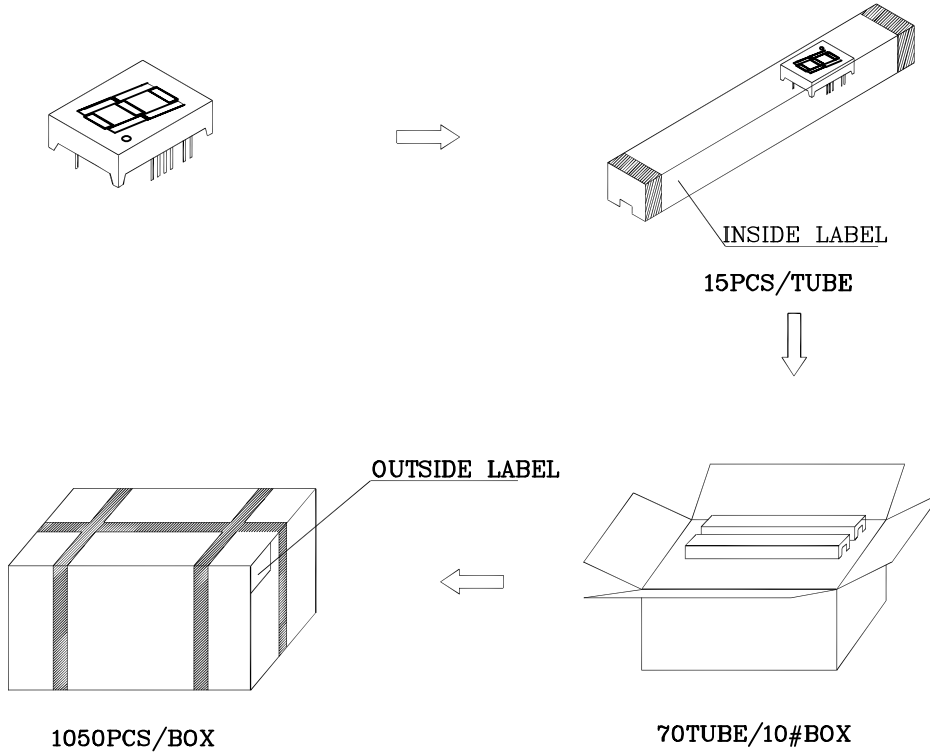
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

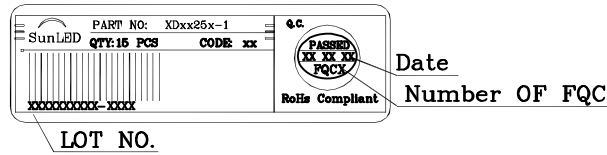
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box

